



Material Content Data Sheet



Sales Product Name		TLE4961-3M		Issued		25. January 2018			
MA#		MA001227990							
Package		PG-SOT23-3-15		Weight*		9.82 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.350	3.56	3.56	35595	35595	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73		
		non noble metal	titanium	7440-32-6	0.004	0.04		367	
		non noble metal	chromium	7440-47-3	0.011	0.11		1101	
wire	noble metal	non noble metal	copper	7440-50-8	3.590	36.56	36.72	365592	367133
		noble metal	gold	7440-57-5	0.019	0.19	0.19	1890	1890
		organic material	carbon black	1333-86-4	0.054	0.55		5463	
encapsulation	plastics	epoxy resin	-	1.153	11.75		117454		
		inorganic material	silicondioxide	60676-86-0	4.157	42.33	54.63	423381	546298
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15240	15240	
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15133	15133	
glue	plastics	epoxy resin	-	0.032	0.33		3274		
		noble metal	silver	7440-22-4	0.152	1.54	1.87	15437	18711
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com